

**IN THE SPECIFICATION:**

Please replace the paragraph beginning at page 1, line 6 with the following amended paragraph:

The present invention relates to a probe used for inspecting electrical characteristics of semiconductor devices having a shape of, e.g., a semiconductor wafer, a method for manufacturing the probe, a probe array, a method for manufacturing the probe array, a method for attaching the probe, an apparatus for attaching the probe, a probe card and a probe array ~~maintenance~~ supporting unit.

Please replace the paragraph beginning at page 2, line 8 with the following amended paragraph:

Technologies disclosed therein are all based on a lithography technology and using same. In the technologies, to arrange the probes correspondently to an array of the plurality of inspecting electrodes, the plurality of probes are formed simultaneously on a surface of a contactor substrate (probe card) made of, e.g., a ceramic, silicon or the like. The probe installed in the probe card includes a contactor electrically contacting with, e.g., the inspecting electrode and a beam maintaining the contactor at a leading end thereof. The probes are arranged on the contactor substrate in a predetermined array, thereby making each of a plurality of contactors electrically contact with a different one of the inspecting electrodes.

Please replace the paragraphs beginning at page 25, line 13 with the following amended paragraphs:

Moreover, in case of the high adhesiveness of the first adhesiveness resin film 11, a process for reducing the adhesiveness is further preferably performed in addition to the heating process described above. The process is performed by radiating the ultraviolet light UV from a side of the first adhesive resin film 11 by using, e.g., an apparatus for radiating the ultraviolet light ~~radiating apparatus~~ UV.

(Fig. 5F) As shown in Fig. 5F, there is performed a process to deteriorate the adhesiveness of the portion of the second adhesive resin film 12, where each probe 4 is not arranged thereon. The process is performed by irradiating the ultraviolet light UV to the second adhesive resin film 12 from a side of the probe 4 with, e.g., the ultraviolet light radiating apparatus [[UV]]. The radiation of the ultraviolet light deteriorates the adhesiveness of a portion of the second adhesive resin film 12, where each probe 4 is not provided thereon. In case of the high adhesiveness of the second adhesiveness resin film 12 to the probe 4, the ultraviolet light may be radiated from the reverse side of the surface thereof, where the probe 4 is provided thereon. The radiation diminishes the adhesiveness of the second adhesive resin film 12 to the probe 4.

Please replace the paragraph beginning at page 29, line 2 with the following amended paragraph:

As exemplified by referring to Figs. 6 and 7, the detection unit 105 includes a first CCD camera 105A photographing the ~~contactor-substrate~~ probe card 1 on the mounting table 101A from upside, a second CCD camera 105B photographing the probe 4 adhered to the second adhesive resin film 12 supported by the supporting unit 103 from downside, a lighting device (not shown) for illuminating each of the ~~contactor-substrate~~ probe card 1 and the probe 4 during photographing thereof, an image processor 109 for processing an image data delivered from the first and the second CCD cameras 105A and 105B, a displaying unit for displaying the image processed by the image processor 109, and controllers 108A and 108B for controlling the first moving unit 102, the second moving unit 104 and the ultrasonic bonder based on the data given from the image processor 109. Each of the first and the second CCD cameras 105A and 105B is installed in a predetermined certain fixed place. The second CCD camera may be installed apart from the mounting table 101A, but preferably fixed near the mounting table (e.g., to the lifting/rotating unit 101B as shown in Fig. 6).

Please replace the paragraph beginning at page 40, line 14 with the following amended paragraph:

Referring to Figs. 9 to 12, there is described a probe array ~~maintenance~~ supporting unit 14 (hereinafter, referred to as a ~~maintenance~~ supporting unit 14) provided with the probe in accordance with the preferred embodiment of the present invention. Fig. 9 shows one of the preferred embodiments of the ~~maintenance~~ supporting unit 14. The supporting unit 14 for supporting the probe array (e.g., the second adhesive resin film and a plurality of probes) 12 includes a first frame shaped structure 14A; a second frame shaped structure 14B overlapped with the first frame shaped structure 14A; and a locking part 14C fastening and fixing the

first and the second frame shaped structures 14A and 14B, which are overlapped with each other.

Please replace the paragraph beginning at page 47, line 13 with the following amended paragraph:

By using the ultrasonic bonder having the protrusion 106D, as shown in Fig. 13B, the base end of the probe 4 is attached to the bump 3. As shown in Fig. 13C, the beam 4B of the probe 4 may be bent toward the contactor at one of the intermediate portion and the base end of the probe 4 and at the same time can be fixed to the bump 3 strongly. By the bending thereof, the leading end of the probe 4 is preferably raised from the ~~contact part~~ contactor by 10  $\mu$ m. After the probes 4 are attached to all the bumps 3 of the card main body 2, if it is necessary to insulate the attached portion, an insulating material 9A is spread on the probe 4 and the bump 3 by a spreading apparatus 111 such as micro-dispenser and the probe card 1 having an insulating film 9 thereon is completed, as shown in Fig. 13D.